Mass measurements with (d,p) transfer reactions



Mark Wallace 06/10/05



Experimental Program

Measure the Mass of ⁶⁴Ge and ⁶⁵As to calculate the Q-Value of ${}^{64}Ge(p,\gamma){}^{65}As$ Use (p,d) Transfer Reactions in Inverse Kinematics [☞]Produce ⁶⁶As and ⁶⁵Ge Beams. **CH**₂ Target for Protons Magnetic Spectrometer to separate reactions products. Measure Deuterons from (p,d) in Charged Particle Array Measure Reaction Angle with Position Sensitive Beam **Tracking Detectors**

How Do We Measure These Nuclear Masses?

${}^{66}As + p \rightarrow d + {}^{65}As$ <u>Using Inverse Kinematics</u>:



(\mathbf{p},\mathbf{d})

Use Heavy Beam Particle.

Heavy Fragment Which Has An **Unknown Mass**

The Proton is in a CH₂ target or a Frozen Hydrogen Target

$$M_{65As}^{2} = M_{66As}^{2} + M_{p}^{2} + M_{d}^{2}$$

$$+2\left[E_{66As}M_{p}-E_{d}M_{p}-E_{66As}M_{d}+\sqrt{E_{66As}^{2}-M_{66As}^{2}}\sqrt{E_{d}^{2}-M_{d}^{2}}Cos(\alpha)\right]$$



Cross Section in Inverse Kinematics



Generating the Radioactive Beam



The S800 Spectrograph

ų.



Resolution



100









Laser Based Alignment System



•Resolution:

- ±0.005° for angular stages.
- 100 microns for distance.

- Designed for precision measurement of detector positions relative to target.
- Adaptable to various configurations and other devices.
- Computer controlled.



Beam Tracking Using Micro Channel Plate Detectors

Magnet



Schematic Construction and Operating Principle of MCP



Resolution of MCP Tracking System

Position: X ~0.35 mm FWHM - Y~0.74 mm FWHM Time: ~ 600 ps FWHM Beam Rates up to 1 MHz Efficiency ~ 90 % at 1 MHz









Silicon Detectors

62.3 x 62.3 mm² Active Area
Pitch 1.95 mm
1024 Pixels per telescope



•Bulk material is n type Interstrip on junction side is 25 μm Interstrip on ohmic side is 40 µm •P+ implant for better interstrip isolation •Depletion voltage for 1.5 mm detector < 500 V •10 guard ring structure on periphery (2mm dead area region)



Particle Identification

Particle ID using EF vs DE



Electronic Readout

developed at Washington University (St. Louis)

With 2000 channels to readout, cost of "traditional" readout is prohibitive.

Application Specific Integrated Circuit



This chip board – + one VME module replaces 32 pre-amp's, 32 Shapers, 32 TDCs and 32 ADCs

Design Includes:

- Multiple Preamps
- Shapers
- Discriminator
- Time to amplitude converters





✓2 different gain internal Charge Sensitive Amplifiers (CSA)

✓100 MeV & 500 MeV dynamic range

✓ Bypass internal CSA for use with higher gain external CSA

✓ Pseudo CFD - Leading edge trigger zero cross discriminator

Computer controlled threshold for each strip

✓ Positive and negative signals

✓On off for each channel

 \checkmark TVC 150 ns & 1 μs

 \checkmark Unity gain Shaper with 1 μs shaping time for both positive and negative signals

 \checkmark 3 computer controlled Inspection points, shown with red dot

✓ Multiplexed output of E & T signals through differential Amp into LVDS flash ADC.

✓ Sparse readout based on hit register, or forced readout of all channels

✓ pulser inputs, even or odd channels

HiRA Electronics Setup Behind Detectors in Vacuum Chamber





Signal Traces from Differential Amplifier to ADC



Chip High Gain Pre-Amplifier



External 60 mV/MeV Pre-Amplifier + ASIC Chip



Simulated ⁶⁴Ge mass spectrum from ⁶⁵Ge(p,d)⁶⁴Ge



Status and Outlook

•Final Test of Entire system July 10th

Initial Test of (p,d)
 experiment July 18th

•Measurement of ⁶⁵As and ⁶⁴Ge August

•Breakup Measurement of ⁶⁹Br

•Measurements of ⁷²Kr, ⁷³Rb in the future

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